

HGA BALLBOND ASSEMBLY WITH WAFER
PROCESS ASSEMBLY FEATURES
ABSTRACT OF THE DISCLOSURE

A method is used for aligning a slider on a gimbal. The gimbal includes a slider opposing face with a flex circuit material on the slider opposing face and a flex on suspension (FOS) bond pad is disposed on the flex circuit material. The slider has a gimbal opposing face and a disc opposing face. Both faces are bounded by a leading edge and a trailing edge. The slider has a forward face along the trailing edge extending between the gimbal opposing face and the disc opposing face. An extended bond pad is formed on the forward face of the slider. A notch is formed on the slider in the forward face adjacent the gimbal opposing face. The slider is placed on the flex circuit material such that the extended bond pad is positioned relative to the FOS bond pad to improve bond strength and static attitude.

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